



Material Composition Declaration

EPC2066

Company Name	Efficient Power Conversion (EPC)	Issue Date:	6/17/2022
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	19.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	16.0990	84.9163	88.1814	849163
	Silicon oxide	7631-86-9	0.1071	0.5647		5647
	Silicon nitride	12033-89-5	0.0271	0.1428		1428
	Gallium nitride	25617-97-4	0.0670	0.3533		3533
	Aluminum	7429-90-5	0.1568	0.8270		8270
	Aluminum nitride	24304-00-5	0.0103	0.0543		543
	Titanium	7440-32-6	0.0036	0.0188		188
	Titanium nitride	25583-20-4	0.0834	0.4399		4399
	Copper	7440-50-8	0.0026	0.0138		138
	Tungsten	7440-33-7	0.0147	0.0774		774
	Polyimide		0.1466	0.7731	7731	
Under Bump Metal	Titanium	7440-32-6	0.0018	0.0097	0.1057	97
	Copper	7440-50-8	0.0182	0.0960		960
Solder Bump	Copper	7440-50-8	0.1820	0.9600	11.7130	9600
	Nickel	7440-02-0	0.1086	0.5726		5726
	Tin	7440-31-5	1.8953	9.9971		99971
	Silver	7440-22-4	0.0347	0.1832		1832
Sum in total:			18.9587	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.